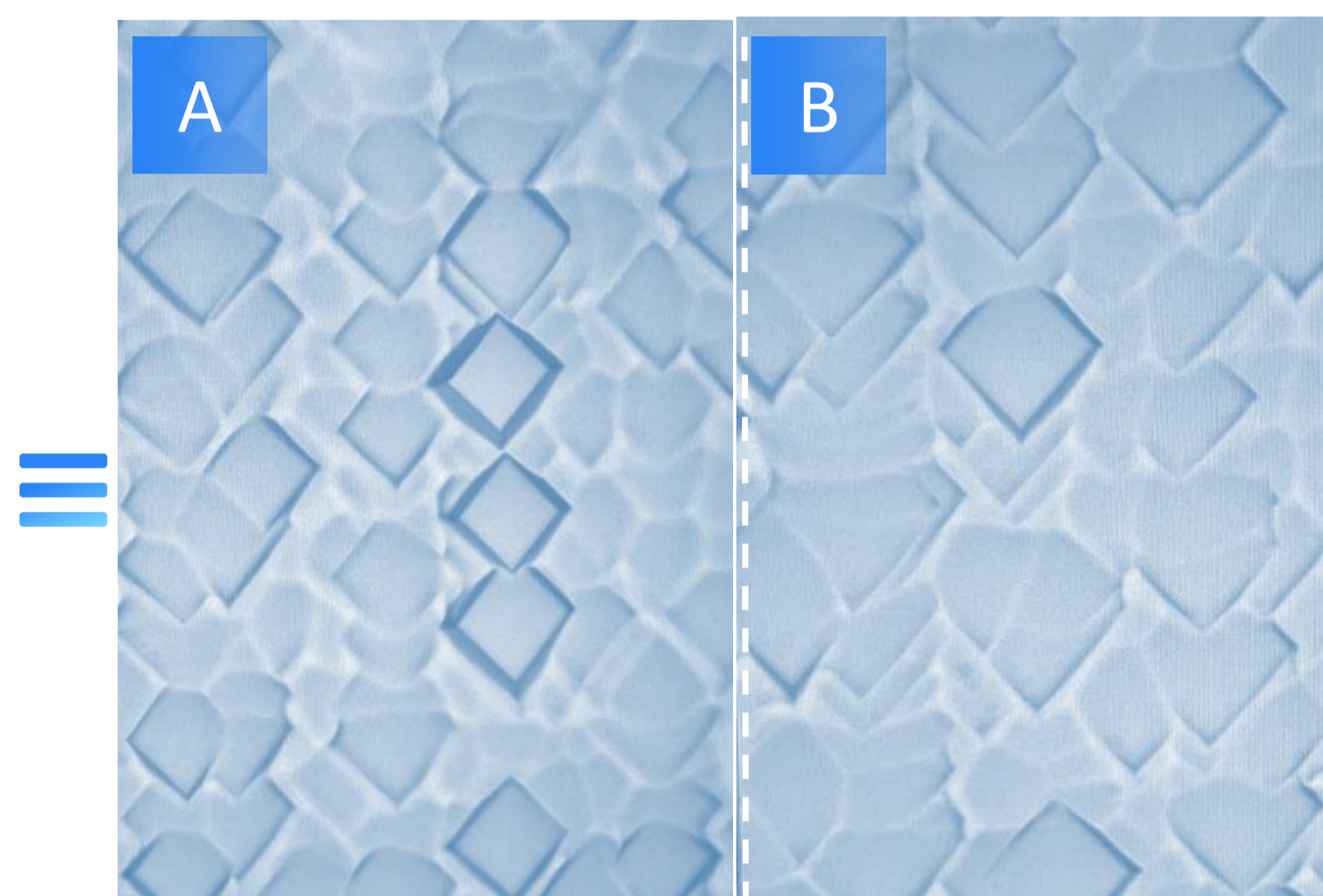


# Alkaline Polishing Additive BPL-719



## Large Window for Etch Weight Control:

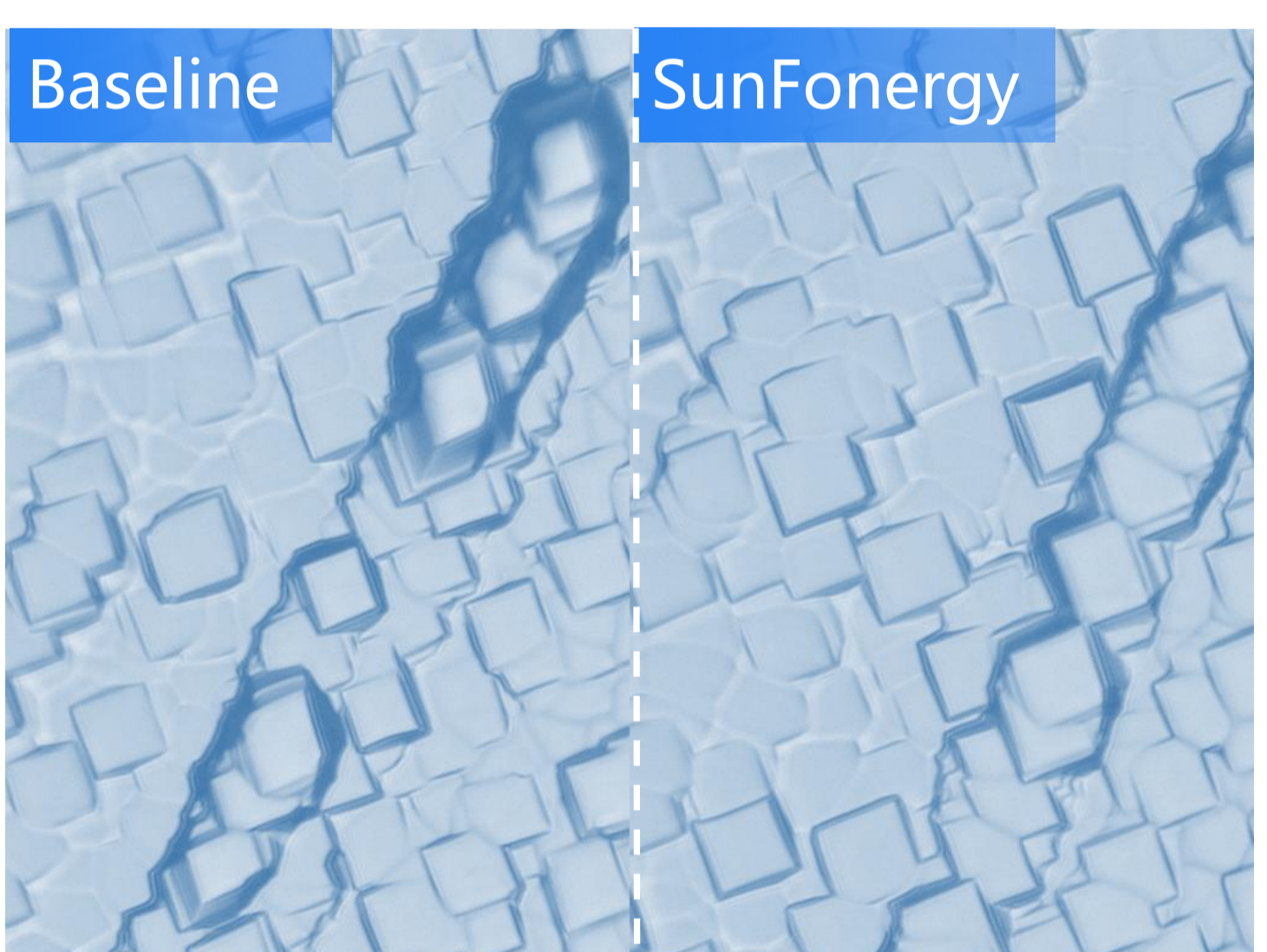
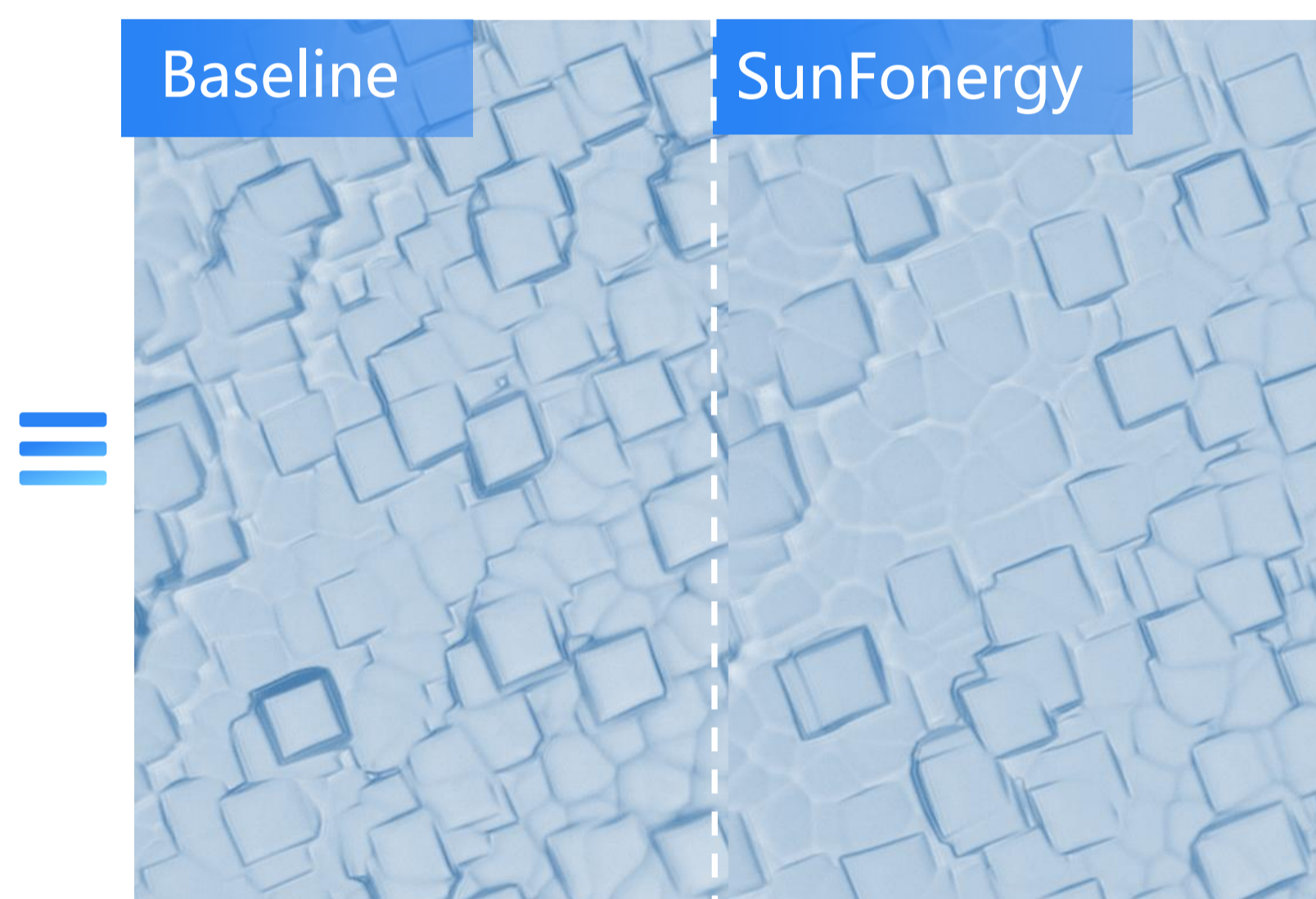
Similar efficiency across different etch weights



**A: 182mm wafer  
0.21g etch weight**  
**B: 182mm wafer  
0.25g etch weight**

## Better Morphology:

More uniform surface, smoother overlays among pyramid bases.



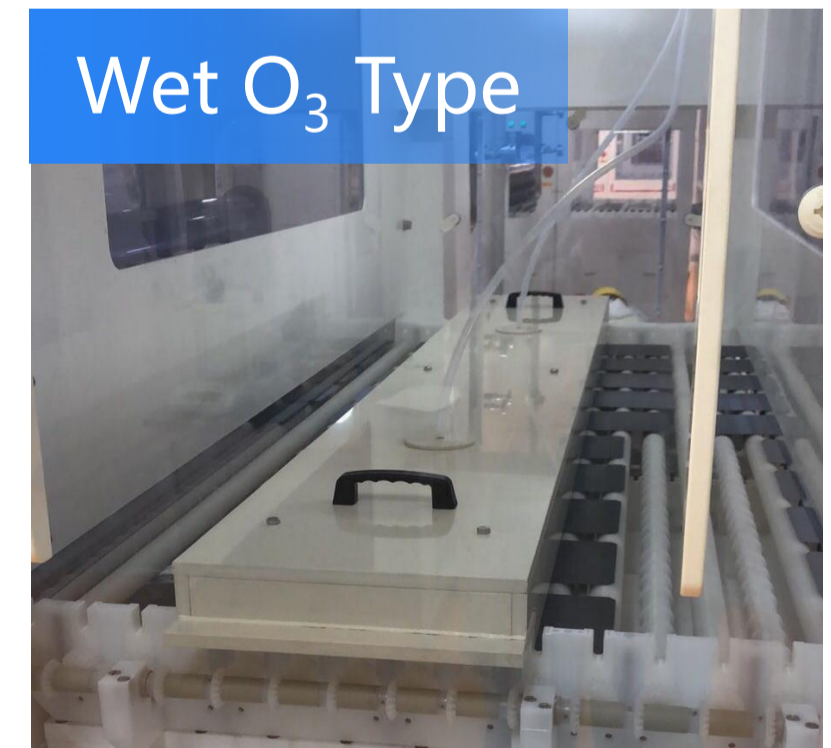
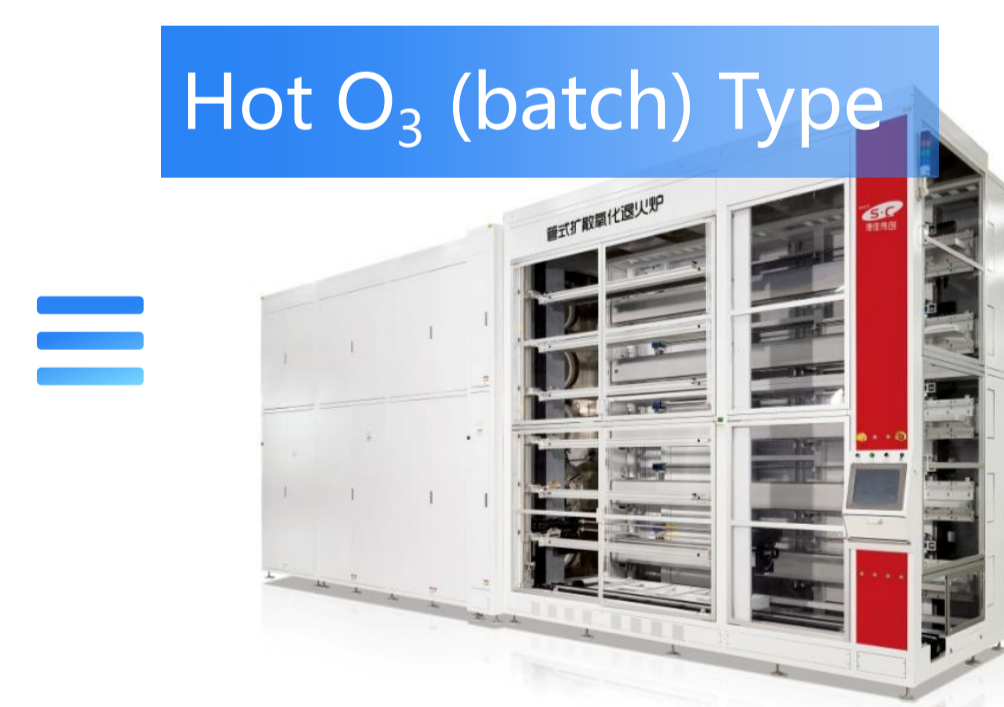
## Higher Efficiency

Higher efficiency than competitors and stable performance throughout lifetime

Item	Eta	Uoc	Isc	FF	IRev2	Rs	Rsh
Baseline	22.88	0.6862	13.496	81.57	0.073	0.0018	663.12
SunFonergy	22.89	0.6869	13.484	81.60	0.078	0.0018	667.21

## High Adaptability:

SunFonergy's additive can be used with both hot O<sub>3</sub> (inline and batch type) and wet O<sub>3</sub> processes.



## Strong Cleaning Power:

SunFonergy's additive can more effectively remove wafer residues, resulting in a cleaner alkaline polishing process.



## More Uniform Surface:

Smoother overlays among polished pyramid bases.



## Cost Effective:

Reduces the post-cleaning bath's alkaline chemical concentration and/or removes the post-cleaning step.



## Strong Front-Side Protection:

SunFonergy's additive offers strong front-side protection under stress-tested conditions (high temperature, long duration, etc).